

PRODUCTION CAPACITY PRINTED CIRCUIT BOARDS FOR PROTOTYPES AND SMALL SERIES

SPECIFICATIONS:

LAYERS NUMBER	1-32 2-10 (RIGID-FLEXIBLE; FLEXIBLE)
LAMINATES AVAILABLE	FR4, ALUMINIUM, TEFLON (PTFE), CERAMIC, CEM-1, CEM-3
MINIMUM LAMINATE THICKNESS	0,2 mm
MAXIMUM LAMINATE THICKNESS	4,8 mm
COPPER THICKNESS	18 µm, 35 µm, 70 µm 105 µm, 140 µm
SURFACE COAT	CHEMICAL GOLD (ENIG), LEAD-FREE AND LEADED HALIDE (HASL), ELECTROLYTIC GOLD (HARD GOLD), CHEMICAL SILVER, CHEMICAL TIN, ORGANIC FLUX COATING (OSP)
AVAILABLE MASK COLOURS	GREEN, WHITE, BLACK, RED, BLUE (ALSO AVAILABLE IN MATT FINISH)
ADDITIONAL COATINGS	TEAR-OFF MASK, GRAPHITE MASK
MINIMUM HOLE DIAMETER	0,2 mm
MINIMUM PATH THICKNESS	18 µm - 0,1 mm 35 µm - 0,15 mm 70 µm - 0,2 mm 105 µm - 0,25 mm
MAXIMUM PANEL SIZE	500 x 675 mm (IN SPECIAL CASES WE CAN DELIVER LONGER PANELS)
MECHANICAL PROCESSING	GRAVERING, MILLING, NOTCHING, HOLE METALLIZATION, TESTING OF CONNECTIONS
VIAS	BLIND, BURIED
IMPEDANCE CONTROL CAPABILITY	± 7% ÷ 10 %
ADDITIONAL OPTIONS	NO DELETIONS, NO SOLDERMASK ENHANCEMENT